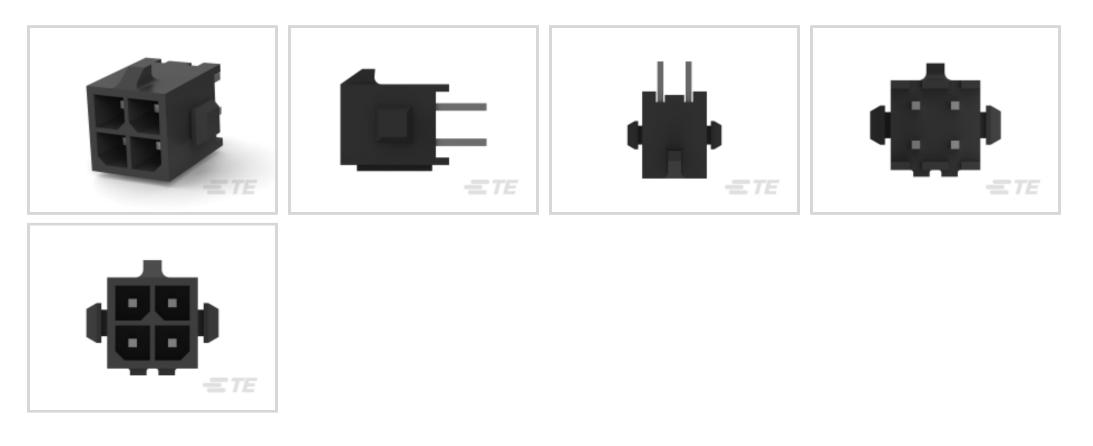


MATE-N-LOK | Micro MATE-N-LOK

TE Internal #: 3-794630-4 PCB Mount Header, Vertical, Wire-to-Board, 4 Position, 3 mm [.118 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, Power, Micro MATE-N-LOK

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



Connector System: Wire-to-Board

Number of Positions: 4

Number of Rows: 2

Centerline (Pitch): 3 mm [.118 in]

PCB Mount Orientation: Vertical

Features

connectivity

Product Type Features

Mixed & Hybrid Header	No
Connector Shape	Rectangular
Connector System	Wire-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Header
Configuration Features	
Number of Power Positions	4
Number of Columns	2
Number of Loaded Positions	4
Connector Contact Load Condition	Fully Loaded
Number of Positions	4
Number of Rows	2

PCB Mount Header, Vertical, Wire-to-Board, 4 Position, 3 mm [.118 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, Power, Micro MATE-N-LOK



PCB Mount Orientation	Vertical
Electrical Characteristics	
Operating Voltage	250 VAC
Body Features	
Primary Product Color	Black
Contact Features	
Contact Mating Area Length	4.15 mm[.163 in]
Contact Size	.64mm
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	2.54 – 7.62 μm[100 – 300 μin]
Contact Layout	Matrix
Contact Underplating Material Thickness	1.27 – 2.54 μm[50 – 100 μin]
Contact Mating Area Plating Material Thickness	2.54 – 7.62 μm[100 – 300 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Square
Contact Mating Area Plating Material Finish	Matte
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Brass
Contact Mating Area Plating Material	Tin
Contact Type	Tab
Contact Current Rating (Max)	5 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	3.18 mm[.125 in]
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Retention	With
Panel Mount Feature	Without
PCB Mount Retention Type	Retention Bump
Mating Retention Type	Locking Tab

PCB Mount Header, Vertical, Wire-to-Board, 4 Position, 3 mm [.118 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, Power, Micro MATE-N-LOK



Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	With
Housing Features	
Mating Entry Location	Тор
Housing Material	High Temperature Nylon
Centerline (Pitch)	3 mm[.118 in]
Dimensions	
Connector Length	10 mm[.394 in]
Connector Height	9.24 mm[.364 in]
Connector Width	8.67 mm[.341 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
Row-to-Row Spacing	3 mm[.118 in]
Usage Conditions	
Operating Temperature (Max)	105 °C[221 °F]
Operating Temperature Range	-40 – 105 °C[-40 – 221 °F]

Operation/Application

Power
Recognized
GWT 750°C (Without Flame)
CNR, USR, VDE
UL E28476, VDE 40005280
UL 94V-0
377
Tray
Compliant

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PCB Mount Header, Vertical, Wire-to-Board, 4 Position, 3 mm [.118 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, Power, Micro MATE-N-LOK



EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

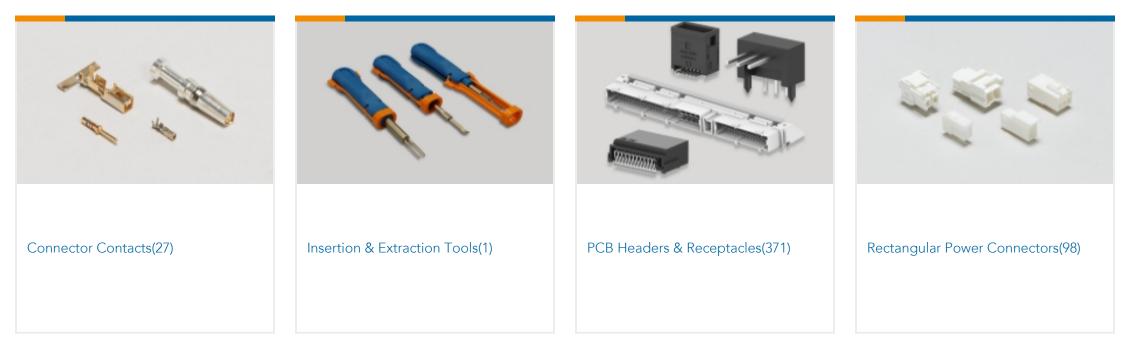
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts



Also in the Series Micro MATE-N-LOK



PCB Mount Header, Vertical, Wire-to-Board, 4 Position, 3 mm [.118 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, Power, Micro MATE-N-LOK



Customers Also Bought



Documents

Product Drawings 04P MICRO MNL ASSY VRT HDR LF

English

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_3-794630-4_H.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_3-794630-4_H.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_3-794630-4_H.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

SOFT_SHELL_PIN_AND_SOCKET_CONNECTORS_CATALOG

English

MICRO MATE-N-LOK CONNECTOR SYSTEM

English

Product Specifications

Application Specification

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PCB Mount Header, Vertical, Wire-to-Board, 4 Position, 3 mm [.118 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, Power, Micro MATE-N-LOK



English
Agency Approvals
VDE Certificate
English